

**VOLUMETRICALLY EFFICIENT ELECTRONIC CIRCUIT MODULE****Abstract of the Disclosure**

5           A miniaturized microelectronic, hybrid circuit package having either a single or  
a multi-layer, flexible, printed circuit substrate with printed conductors interconnecting  
a plurality of integrated circuit (IC) dies with a ball grid array (BGA) of contacts. The  
IC dies are arranged on parallel strips defined between preferential fold zones formed  
in the substrate. The dies are over molded with plastic that is shaped to facilitate the  
10       substrate being folded to form a polyhedron. When so folded, the over molded IC dies  
face inward and BGA is exposed on an outwardly facing surface to facilitate  
attachment of the folded package to a motherboard.